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What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, IrDA, LINbus, MMC/SD/SDIO, QSPI, SmartCard, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	121
Program Memory Size	2MB (2M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	152-VFBGA
Supplier Device Package	152-BGA (8x8)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b820f2048gl152-br

Ordering Code	Flash (kB)	RAM (kB)	DC-DC Converter	USB	Ethernet	QSPI	SDIO	LCD	GPIO	Package	Temp Range
EFM32GG11B520F2048GQ64-A	2048	512	Yes	No	No	No	No	Yes	50	QFP64	-40 to +85°C
EFM32GG11B510F2048GQ64-A	2048	384	Yes	No	No	No	No	Yes	50	QFP64	-40 to +85°C
EFM32GG11B520F2048GM64-A	2048	512	Yes	No	No	No	No	Yes	53	QFN64	-40 to +85°C
EFM32GG11B510F2048GM64-A	2048	384	Yes	No	No	No	No	Yes	53	QFN64	-40 to +85°C
EFM32GG11B520F2048IQ64-A	2048	512	Yes	No	No	No	No	Yes	50	QFP64	-40 to +125°C
EFM32GG11B510F2048IQ64-A	2048	384	Yes	No	No	No	No	Yes	50	QFP64	-40 to +125°C
EFM32GG11B520F2048IM64-A	2048	512	Yes	No	No	No	No	Yes	53	QFN64	-40 to +125°C
EFM32GG11B510F2048IM64-A	2048	384	Yes	No	No	No	No	Yes	53	QFN64	-40 to +125°C
EFM32GG11B420F2048GL120-A	2048	512	No	Yes	Yes	Yes	Yes	Yes	93	BGA120	-40 to +85°C
EFM32GG11B420F2048IL120-A	2048	512	No	Yes	Yes	Yes	Yes	Yes	93	BGA120	-40 to +125°C
EFM32GG11B420F2048GL112-A	2048	512	No	Yes	Yes	Yes	Yes	Yes	87	BGA112	-40 to +85°C
EFM32GG11B420F2048IL112-A	2048	512	No	Yes	Yes	Yes	Yes	Yes	87	BGA112	-40 to +125°C
EFM32GG11B420F2048GQ100-A	2048	512	No	Yes	Yes	Yes	Yes	Yes	83	QFP100	-40 to +85°C
EFM32GG11B420F2048IQ100-A	2048	512	No	Yes	Yes	Yes	Yes	Yes	83	QFP100	-40 to +125°C
EFM32GG11B420F2048GQ64-A	2048	512	No	Yes	Yes	Yes	Yes	Yes	50	QFP64	-40 to +85°C
EFM32GG11B420F2048GM64-A	2048	512	No	Yes	Yes	Yes	Yes	Yes	53	QFN64	-40 to +85°C
EFM32GG11B420F2048IQ64-A	2048	512	No	Yes	Yes	Yes	Yes	Yes	50	QFP64	-40 to +125°C
EFM32GG11B420F2048IM64-A	2048	512	No	Yes	Yes	Yes	Yes	Yes	53	QFN64	-40 to +125°C
EFM32GG11B320F2048GL112-A	2048	512	No	No	No	No	No	Yes	90	BGA112	-40 to +85°C
EFM32GG11B310F2048GL112-A	2048	384	No	No	No	No	No	Yes	90	BGA112	-40 to +85°C
EFM32GG11B320F2048GQ100-A	2048	512	No	No	No	No	No	Yes	86	QFP100	-40 to +85°C
EFM32GG11B310F2048GQ100-A	2048	384	No	No	No	No	No	Yes	86	QFP100	-40 to +85°C
EFM32GG11B120F2048GQ64-A	2048	512	No	No	No	No	No	No	53	QFP64	-40 to +85°C
EFM32GG11B110F2048GQ64-A	2048	384	No	No	No	No	No	No	53	QFP64	-40 to +85°C
EFM32GG11B120F2048GM64-A	2048	512	No	No	No	No	No	No	56	QFN64	-40 to +85°C
EFM32GG11B110F2048GM64-A	2048	384	No	No	No	No	No	No	56	QFN64	-40 to +85°C
EFM32GG11B120F2048IQ64-A	2048	512	No	No	No	No	No	No	53	QFP64	-40 to +125°C
EFM32GG11B110F2048IQ64-A	2048	384	No	No	No	No	No	No	53	QFP64	-40 to +125°C
EFM32GG11B120F2048IM64-A	2048	512	No	No	No	No	No	No	56	QFN64	-40 to +125°C
EFM32GG11B110F2048IM64-A	2048	384	No	No	No	No	No	No	56	QFN64	-40 to +125°C

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Frequency limits	f _{HFRCO_BAND}	FREQRANGE = 0, FINETUNING = 0	1	—	10	MHz
		FREQRANGE = 3, FINETUNING = 0	2	—	17	MHz
		FREQRANGE = 6, FINETUNING = 0	4	—	30	MHz
		FREQRANGE = 7, FINETUNING = 0	5	—	34	MHz
		FREQRANGE = 8, FINETUNING = 0	7	—	42	MHz
		FREQRANGE = 10, FINETUNING = 0	12	—	58	MHz
		FREQRANGE = 11, FINETUNING = 0	15	—	68	MHz
		FREQRANGE = 12, FINETUNING = 0	18	—	83	MHz
		FREQRANGE = 13, FINETUNING = 0	24	—	100	MHz
		FREQRANGE = 14, FINETUNING = 0	28	—	119	MHz
		FREQRANGE = 15, FINETUNING = 0	33	—	138	MHz
		FREQRANGE = 16, FINETUNING = 0	43	—	163	MHz

Note:

1. Maximum DPLL lock time $\sim 6 \times (M+1) \times t_{\text{REF}}$, where t_{REF} is the reference clock period.

4.1.14 Analog to Digital Converter (ADC)

Specified at 1 Msps, ADCCLK = 16 MHz, BIASPROG = 0, GPBIASACC = 0, unless otherwise indicated.

Table 4.22. Analog to Digital Converter (ADC)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Resolution	V _{RESOLUTION}		6	—	12	Bits
Input voltage range ⁵	V _{ADCIN}	Single ended	—	—	V _{FS}	V
		Differential	-V _{FS} /2	—	V _{FS} /2	V
Input range of external reference voltage, single ended and differential	V _{ADCREFIN_P}		1	—	V _{AVDD}	V
Power supply rejection ²	PSRR _{ADC}	At DC	—	80	—	dB
Analog input common mode rejection ratio	CMRR _{ADC}	At DC	—	80	—	dB
Current from all supplies, using internal reference buffer. Continuous operation. WAR-MUPMODE ⁴ = KEEPADC-WARM	I _{ADC_CONTINUOUS_LP}	1 Msps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 1 ³	—	270	TBD	μA
		250 ksps / 4 MHz ADCCLK, BIASPROG = 6, GPBIASACC = 1 ³	—	125	—	μA
		62.5 ksps / 1 MHz ADCCLK, BIASPROG = 15, GPBIASACC = 1 ³	—	80	—	μA
Current from all supplies, using internal reference buffer. Duty-cycled operation. WAR-MUPMODE ⁴ = NORMAL	I _{ADC_NORMAL_LP}	35 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 1 ³	—	45	—	μA
		5 ksps / 16 MHz ADCCLK BIASPROG = 0, GPBIASACC = 1 ³	—	8	—	μA
Current from all supplies, using internal reference buffer. Duty-cycled operation. AWARMUPMODE ⁴ = KEEP-INSTANDBY or KEEPIN-SLOWACC	I _{ADC_STANDBY_LP}	125 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 1 ³	—	105	—	μA
		35 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 1 ³	—	70	—	μA
Current from all supplies, using internal reference buffer. Continuous operation. WAR-MUPMODE ⁴ = KEEPADC-WARM	I _{ADC_CONTINUOUS_HP}	1 Msps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 ³	—	325	—	μA
		250 ksps / 4 MHz ADCCLK, BIASPROG = 6, GPBIASACC = 0 ³	—	175	—	μA
		62.5 ksps / 1 MHz ADCCLK, BIASPROG = 15, GPBIASACC = 0 ³	—	125	—	μA
Current from all supplies, using internal reference buffer. Duty-cycled operation. WAR-MUPMODE ⁴ = NORMAL	I _{ADC_NORMAL_HP}	35 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 ³	—	85	—	μA
		5 ksps / 16 MHz ADCCLK BIASPROG = 0, GPBIASACC = 0 ³	—	16	—	μA
Current from all supplies, using internal reference buffer. Duty-cycled operation. AWARMUPMODE ⁴ = KEEP-INSTANDBY or KEEPIN-SLOWACC	I _{ADC_STANDBY_HP}	125 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 ³	—	160	—	μA
		35 ksps / 16 MHz ADCCLK, BIASPROG = 0, GPBIASACC = 0 ³	—	125	—	μA
Current from HFPERCLK	I _{ADC_CLK}	HFPERCLK = 16 MHz	—	180	—	μA

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Note: 1. ACMPVDD is a supply chosen by the setting in ACMPn_CTRL_PWRSEL and may be IOVDD, AVDD or DVDD. 2. The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference. $I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF}$. 3. ± 100 mV differential drive. 4. In ACMPn_CTRL register. 5. In ACMPn_HYSTERESIS registers. 6. In ACMPn_INPUTSEL register.						

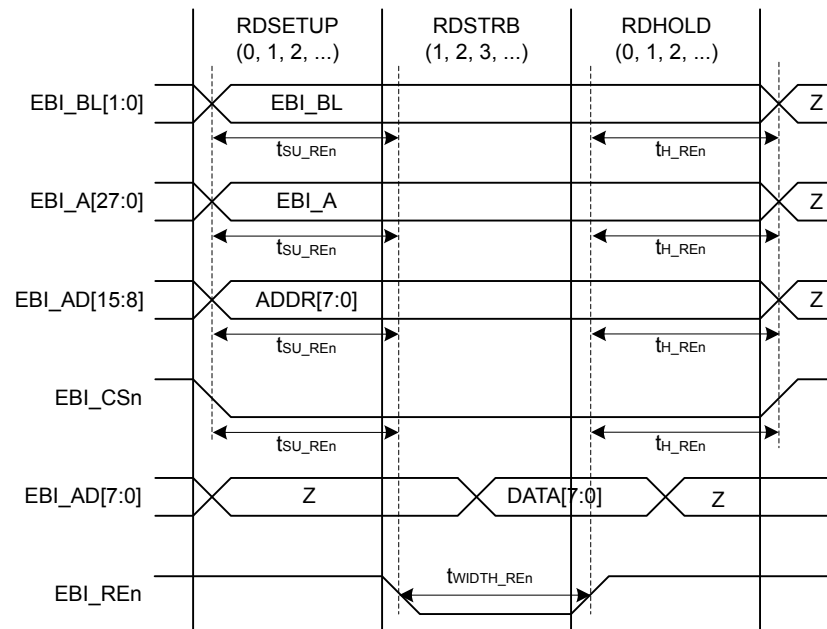


Figure 4.5. EBI Read Enable Output Timing Diagram

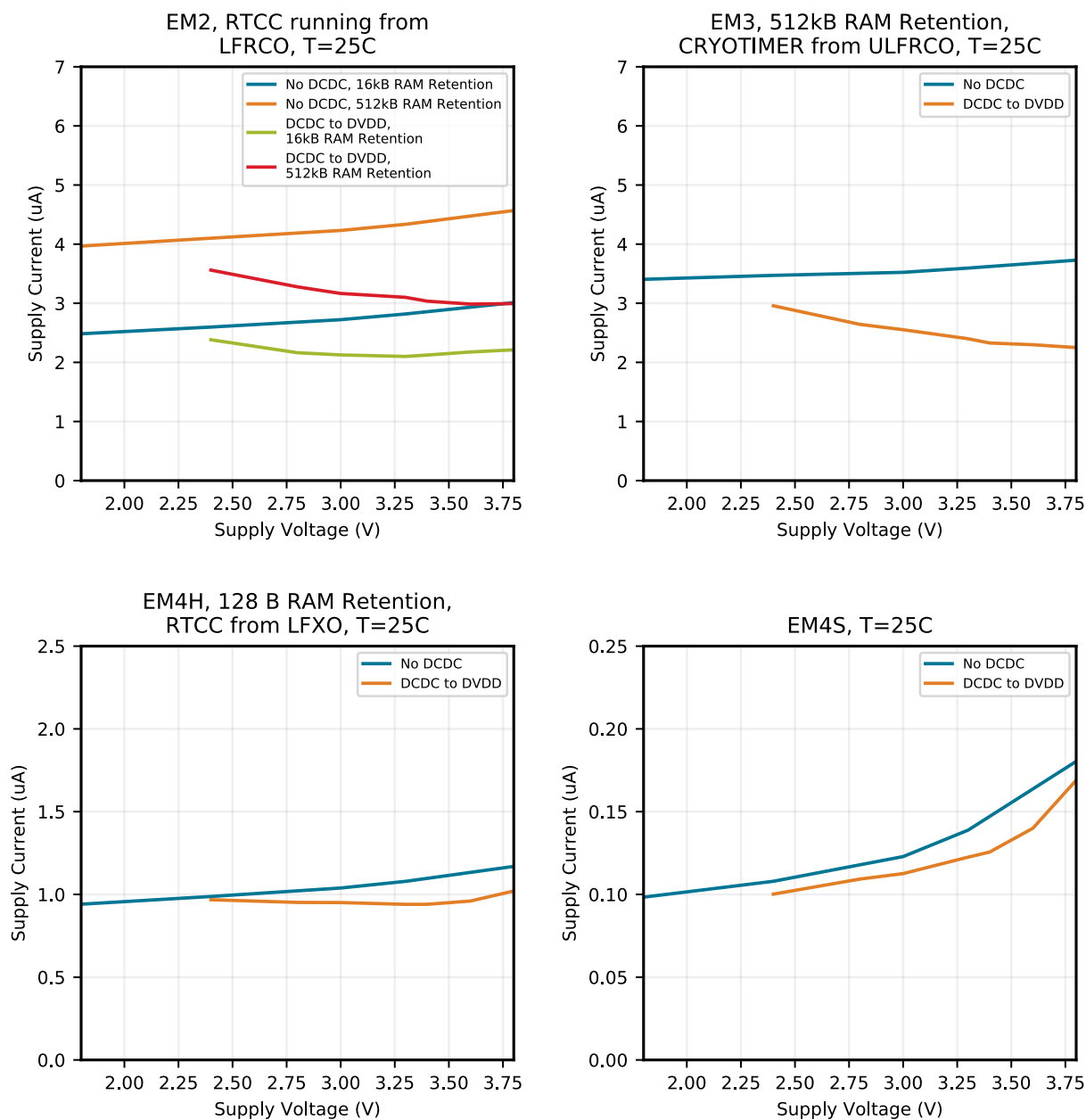


Figure 4.28. EM2, EM3, EM4H and EM4S Typical Supply Current vs. Supply

5.10 EFM32GG11B4xx in QFP100 Device Pinout

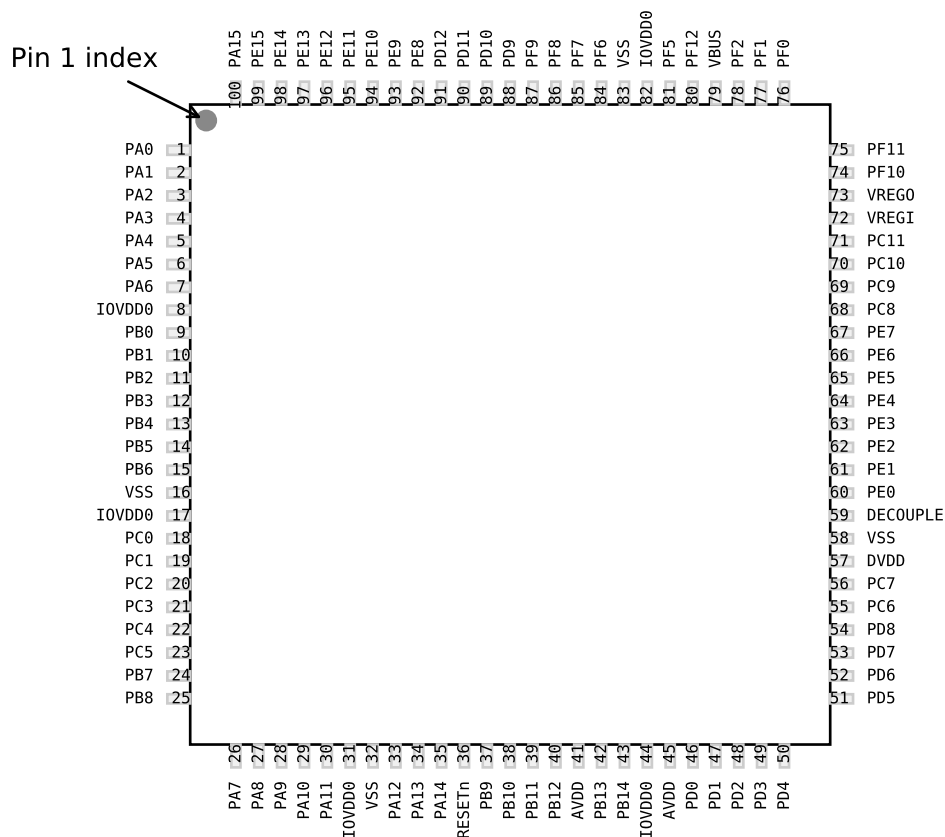


Figure 5.10. EFM32GG11B4xx in QFP100 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.10. EFM32GG11B4xx in QFP100 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
PA6	7	GPIO	IOVDD0	8 17 31 44 82	Digital IO power supply 0.
PB0	9	GPIO	PB1	10	GPIO

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PH14	BUSACMP3Y BU-SACMP3X	EBI_A26 #2	TIM5_CC1 #2 WTIM1_CC2 #7 PCNT2_S0IN #7	US5_CTS #3 U1_RTS #5 I2C1_SCL #6	
PH15	BUSACMP3Y BU-SACMP3X	EBI_A27 #2	TIM5_CC2 #2 WTIM1_CC3 #7 PCNT2_S1IN #6	US5_RTS #3	
PD2	BUSADC0Y BU-SADC0X	EBI_A06 #1 EBI_A15 #3 EBI_A27 #0	TIM0_CC1 #2 TIM6_CC1 #6 WTIM1_CC0 #1	US1_CLK #1 LEU1_TX #2	DBG_SWO #3
PD7	BUSADC0Y BU-SADC0X ADC0_EXTN ADC1_EXTN OPA1_N	EBI_A11 #1 EBI_A20 #3	TIM1_CC1 #4 WTIM1_CC1 #2 LE- TIM0_OUT1 #0 PCNT0_S1IN #3	US1_TX #2 US3_CLK #1 U0_TX #6 I2C0_SCL #1	CMU_CLK0 #2 LES_ALTEX1 ACMP1_O #2 ETM_TCLK #0
PB8	LFXTAL_N		TIM0_CDTI1 #4 TIM1_CC1 #3	US0_RX #4 US1_CS #0 US4_RX #0 U0_RTS #4	CMU_CLKI0 #2 PRS_CH23 #0
PC4	BUSACMP0Y BU-SACMP0X OPA0_P	EBI_AD11 #1 EBI_ALE #2 EBI_NANDREn #3 EBI_A26 #0	TIM0_CC0 #5 TIM0_CDTI2 #3 TIM2_CC2 #5 LE- TIM0_OUT0 #3 PCNT1_S0IN #3	SDIO_CD #1 US2_CLK #0 US4_CLK #0 U0_TX #4 U1_CTS #4 I2C1_SDA #0	LES_CH4 PRS_CH18 #2 GPIO_EM4WU6
PA7	BUSAY BUSBX LCD_SEG35	EBI_AD13 #1 EBI_A01 #3 EBI_CSTFT #0	TIM0_CC2 #5 LE- TIM1_OUT0 #0 PCNT1_S0IN #4	US2_TX #2 US4_CTS #0 US5_RX #1	PRS_CH7 #1
PA10	BUSBY BUSAX LCD_SEG38	EBI_CS0 #1 EBI_A04 #3 EBI_VSNC #0	TIM2_CC2 #0 TIM0_CC2 #6 WTIM2_CC1 #0	US2_CS #2	PRS_CH10 #0
PA12	BUSBY BUSAX	EBI_CS2 #1 EBI_REn #2 EBI_A00 #0 EBI_A06 #3	TIM2_CC0 #1 WTIM0_CDTI0 #2 WTIM2_CC0 #1 LE- TIM1_OUT0 #2 PCNT1_S0IN #5	CAN1_RX #5 US0_CLK #5 US2_RTS #2	CMU_CLK0 #5 PRS_CH12 #0 ACMP1_O #3
PA14	BUSBY BUSAX LCD_BEXT	EBI_REn #1 EBI_A02 #0 EBI_A08 #3	TIM2_CC2 #1 WTIM0_CDTI2 #2 WTIM2_CC2 #1 LE- TIM1_OUT1 #2	US1_TX #6 US2_RX #3 US3_RTS #2	PRS_CH14 #0 ACMP1_O #4
PB11	BUSAY BUSBX VDAC0_OUT0 / OPA0_OUT IDAC0_OUT	EBI_BL1 #2 EBI_A02 #1 EBI_A11 #3	TIM0_CDTI2 #4 TIM1_CC2 #3 WTIM2_CC2 #2 LE- TIM0_OUT0 #1 PCNT0_S1IN #7 PCNT1_S0IN #6	US0_CTS #5 US1_CLK #5 US2_CS #3 US5_CLK #0 U1_CTS #2 I2C1_SDA #1	CMU_CLK1 #5 CMU_CLKI0 #7 PRS_CH21 #2 ACMP0_O #3 GPIO_EM4WU7
PH1	BUSADC1Y BU-SADC1X	EBI_DTEN #2		US0_RTS #6 LEU1_RX #5	
PH4	BUSADC1Y BU-SADC1X	EBI_A16 #2	TIM6_CC2 #3 WTIM2_CC0 #6	US4_TX #4	
PH7	BUSADC1Y BU-SADC1X	EBI_A19 #2	TIM6_CDTI2 #3 WTIM2_CC0 #7	US4_CS #4	
PH10	BUSACMP3Y BU-SACMP3X	EBI_A22 #2	TIM6_CC2 #4 WTIM1_CC2 #6	US5_TX #3	

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
EBI_AD08	0: PA15 1: PC1 2: PG8		External Bus Interface (EBI) address and data input / output pin 08.
EBI_AD09	0: PA0 1: PC2 2: PG9		External Bus Interface (EBI) address and data input / output pin 09.
EBI_AD10	0: PA1 1: PC3 2: PG10		External Bus Interface (EBI) address and data input / output pin 10.
EBI_AD11	0: PA2 1: PC4 2: PG11		External Bus Interface (EBI) address and data input / output pin 11.
EBI_AD12	0: PA3 1: PC5 2: PG12		External Bus Interface (EBI) address and data input / output pin 12.
EBI_AD13	0: PA4 1: PA7 2: PG13		External Bus Interface (EBI) address and data input / output pin 13.
EBI_AD14	0: PA5 1: PA8 2: PG14		External Bus Interface (EBI) address and data input / output pin 14.
EBI_AD15	0: PA6 1: PA9 2: PG15		External Bus Interface (EBI) address and data input / output pin 15.
EBI_ALE	0: PF3 1: PB9 2: PC4 3: PB5	4: PC11 5: PC11	External Bus Interface (EBI) Address Latch Enable output.
EBI_ARDY	0: PF2 1: PD13 2: PB15 3: PB4	4: PC13 5: PF10	External Bus Interface (EBI) Hardware Ready Control input.
EBI_BL0	0: PF6 1: PF8 2: PB10 3: PC1	4: PF6 5: PF6	External Bus Interface (EBI) Byte Lane/Enable pin 0.
EBI_BL1	0: PF7 1: PF9 2: PB11 3: PC3	4: PF7 5: PF7	External Bus Interface (EBI) Byte Lane/Enable pin 1.
EBI_CS0	0: PD9 1: PA10 2: PC0 3: PB0	4: PE8	External Bus Interface (EBI) Chip Select output 0.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
EBI_CS1	0: PD10 1: PA11 2: PC1 3: PB1	4: PE9	External Bus Interface (EBI) Chip Select output 1.
EBI_CS2	0: PD11 1: PA12 2: PC2 3: PB2	4: PE10	External Bus Interface (EBI) Chip Select output 2.
EBI_CS3	0: PD12 1: PB15 2: PC3 3: PB3	4: PE11	External Bus Interface (EBI) Chip Select output 3.
EBI_CSTFT	0: PA7 1: PF6 2: PB12 3: PA0		External Bus Interface (EBI) Chip Select output TFT.
EBI_DCLK	0: PA8 1: PF7 2: PH0 3: PA1		External Bus Interface (EBI) TFT Dot Clock pin.
EBI_DTEN	0: PA9 1: PD9 2: PH1 3: PA2		External Bus Interface (EBI) TFT Data Enable pin.
EBI_HSNCR	0: PA11 1: PD11 2: PH3 3: PA4		External Bus Interface (EBI) TFT Horizontal Synchronization pin.
EBI_NANDREN	0: PC3 1: PD15 2: PB9 3: PC4	4: PC15 5: PF12	External Bus Interface (EBI) NAND Read Enable output.
EBI_NANDWEN	0: PC5 1: PD14 2: PA13 3: PC2	4: PC14 5: PF11	External Bus Interface (EBI) NAND Write Enable output.
EBI_REN	0: PF5 1: PA14 2: PA12 3: PC0	4: PF9 5: PF5	External Bus Interface (EBI) Read Enable output.
EBI_VSNCR	0: PA10 1: PD10 2: PH2 3: PA3		External Bus Interface (EBI) TFT Vertical Synchronization pin.
EBI_WEN	0: PF4 1: PA13 2: PC5 3: PB6	4: PF8 5: PF4	External Bus Interface (EBI) Write Enable output.
ETH_MDC	0: PB4 1: PD14 2: PC1 3: PA6		Ethernet Management Data Clock.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
US1_CTS	0: PB9 1: PD4 2: PF3 3: PC6	4: PC12 5: PB13 6: PH2	USART1 Clear To Send hardware flow control input.
US1_RTS	0: PB10 1: PD5 2: PF4 3: PC7	4: PC13 5: PB14 6: PH3	USART1 Request To Send hardware flow control output.
US1_RX	0: PC1 1: PD1 2: PD6 3: PF7	4: PC2 5: PA0 6: PA2	USART1 Asynchronous Receive. USART1 Synchronous mode Master Input / Slave Output (MISO).
US1_TX	0: PC0 1: PD0 2: PD7 3: PF6	4: PC1 5: PF2 6: PA14	USART1 Asynchronous Transmit. Also used as receive input in half duplex communication. USART1 Synchronous mode Master Output / Slave Input (MOSI).
US2_CLK	0: PC4 1: PB5 2: PA9 3: PA15	4: PF8 5: PF2	USART2 clock input / output.
US2_CS	0: PC5 1: PB6 2: PA10 3: PB11	4: PF9 5: PF5	USART2 chip select input / output.
US2_CTS	0: PC1 1: PB12 2: PA11 3: PB10	4: PC12 5: PD6	USART2 Clear To Send hardware flow control input.
US2_RTS	0: PC0 1: PB15 2: PA12 3: PC14	4: PC13 5: PD8	USART2 Request To Send hardware flow control output.
US2_RX	0: PC3 1: PB4 2: PA8 3: PA14	4: PF7 5: PF1	USART2 Asynchronous Receive. USART2 Synchronous mode Master Input / Slave Output (MISO).
US2_TX	0: PC2 1: PB3 2: PA7 3: PA13	4: PF6 5: PF0	USART2 Asynchronous Transmit. Also used as receive input in half duplex communication. USART2 Synchronous mode Master Output / Slave Input (MOSI).
US3_CLK	0: PA2 1: PD7 2: PD4 3: PG8	4: PG2 5: PI14	USART3 clock input / output.
US3_CS	0: PA3 1: PE4 2: PC14 3: PC0	4: PG3 5: PI15	USART3 chip select input / output.
US3_CTS	0: PA4 1: PE5 2: PD6 3: PG10	4: PG4 5: PG9	USART3 Clear To Send hardware flow control input.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
US3_RTS	0: PA5 1: PC1 2: PA14 3: PC15	4: PG5 5: PG11	USART3 Request To Send hardware flow control output.
US3_RX	0: PA1 1: PE7 2: PB7 3: PG7	4: PG1 5: PI13	USART3 Asynchronous Receive. USART3 Synchronous mode Master Input / Slave Output (MISO).
US3_TX	0: PA0 1: PE6 2: PB3 3: PG6	4: PG0 5: PI12	USART3 Asynchronous Transmit. Also used as receive input in half duplex communication. USART3 Synchronous mode Master Output / Slave Input (MOSI).
US4_CLK	0: PC4 1: PD11 2: PI2 3: PI8	4: PH6	USART4 clock input / output.
US4_CS	0: PC5 1: PD12 2: PI3 3: PI9	4: PH7	USART4 chip select input / output.
US4_CTS	0: PA7 1: PD13 2: PI4 3: PI10	4: PH8	USART4 Clear To Send hardware flow control input.
US4_RTS	0: PA8 1: PD14 2: PI5 3: PI11	4: PH9	USART4 Request To Send hardware flow control output.
US4_RX	0: PB8 1: PD10 2: PI1 3: PI7	4: PH5	USART4 Asynchronous Receive. USART4 Synchronous mode Master Input / Slave Output (MISO).
US4_TX	0: PB7 1: PD9 2: PI0 3: PI6	4: PH4	USART4 Asynchronous Transmit. Also used as receive input in half duplex communication. USART4 Synchronous mode Master Output / Slave Input (MOSI).
US5_CLK	0: PB11 1: PD13 2: PF13 3: PH12		USART5 clock input / output.
US5_CS	0: PB13 1: PD14 2: PF12 3: PH13		USART5 chip select input / output.
US5_CTS	0: PB14 1: PD15 2: PF11 3: PH14		USART5 Clear To Send hardware flow control input.
US5_RTS	0: PB12 1: PB15 2: PF10 3: PH15		USART5 Request To Send hardware flow control output.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
WTIM0_CC2	0: PE6 1: PD14 2: PG4 3: PG10	4: PF1 5: PB2 6: PB5 7: PC3	Wide timer 0 Capture Compare input / output channel 2.
WTIM0_CDTI0	0: PE10 1: PD15 2: PA12 3: PG11	4: PD4	Wide timer 0 Complimentary Dead Time Insertion channel 0.
WTIM0_CDTI1	0: PE11 1: PG0 2: PA13 3: PG12	4: PD5	Wide timer 0 Complimentary Dead Time Insertion channel 1.
WTIM0_CDTI2	0: PE12 1: PG1 2: PA14 3: PG13	4: PD6	Wide timer 0 Complimentary Dead Time Insertion channel 2.
WTIM1_CC0	0: PB13 1: PD2 2: PD6 3: PC7	4: PE3 5: PE7 6: PH8 7: PH12	Wide timer 1 Capture Compare input / output channel 0.
WTIM1_CC1	0: PB14 1: PD3 2: PD7 3: PE0	4: PE4 5: PI0 6: PH9 7: PH13	Wide timer 1 Capture Compare input / output channel 1.
WTIM1_CC2	0: PD0 1: PD4 2: PD8 3: PE1	4: PE5 5: PI1 6: PH10 7: PH14	Wide timer 1 Capture Compare input / output channel 2.
WTIM1_CC3	0: PD1 1: PD5 2: PC6 3: PE2	4: PE6 5: PI2 6: PH11 7: PH15	Wide timer 1 Capture Compare input / output channel 3.
WTIM2_CC0	0: PA9 1: PA12 2: PB9 3: PB12	4: PG14 5: PD3 6: PH4 7: PH7	Wide timer 2 Capture Compare input / output channel 0.
WTIM2_CC1	0: PA10 1: PA13 2: PB10 3: PG12	4: PG15 5: PD4 6: PH5 7: PH8	Wide timer 2 Capture Compare input / output channel 1.
WTIM2_CC2	0: PA11 1: PA14 2: PB11 3: PG13	4: PH0 5: PD5 6: PH6 7: PH9	Wide timer 2 Capture Compare input / output channel 2.
WTIM3_CC0	0: PD9 1: PC8 2: PC11 3: PC14	4: PI3 5: PI6 6: PB6 7: PF13	Wide timer 3 Capture Compare input / output channel 0.
WTIM3_CC1	0: PD10 1: PC9 2: PC12 3: PF10	4: PI4 5: PI7 6: PF4 7: PF14	Wide timer 3 Capture Compare input / output channel 1.

6.2 BGA192 PCB Land Pattern

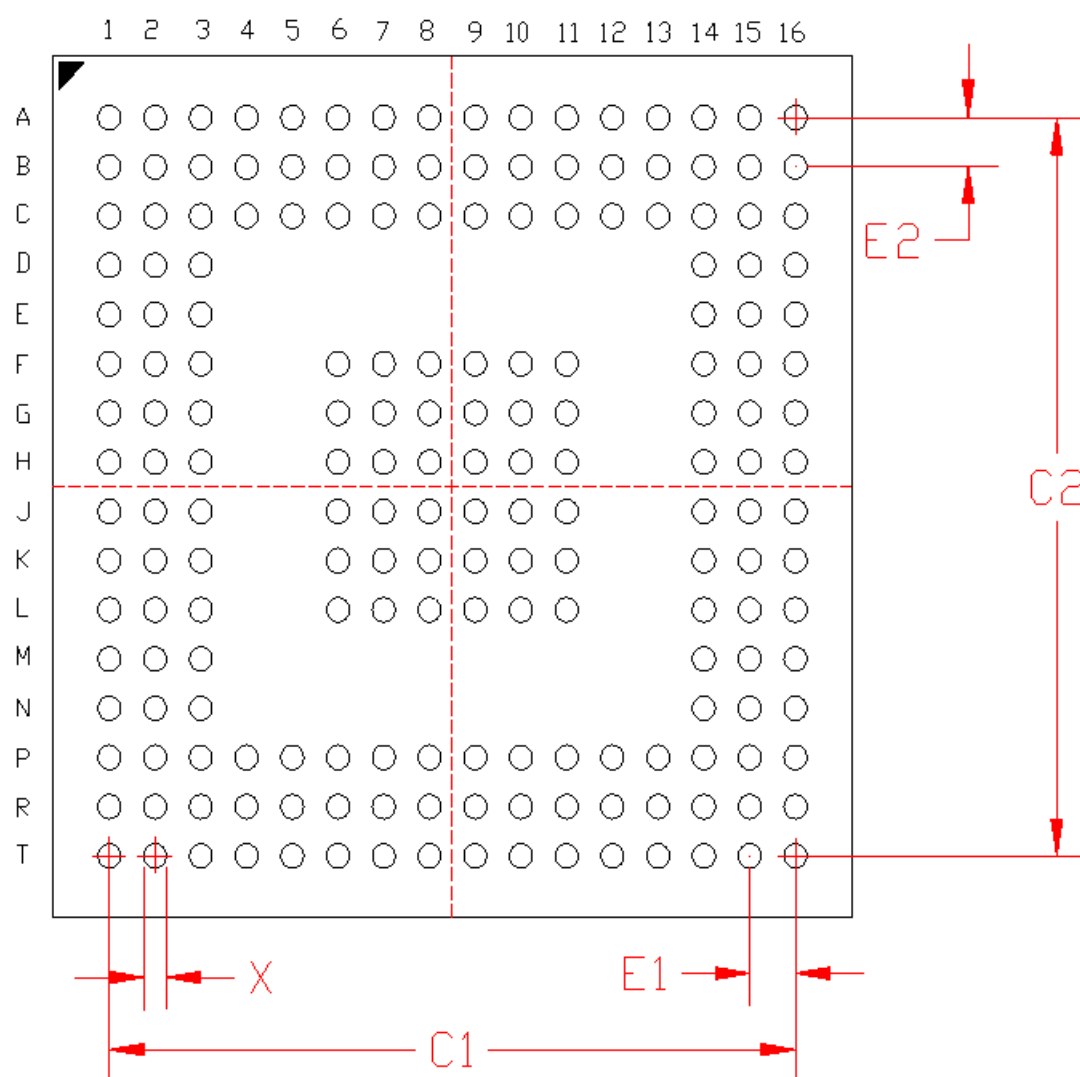


Figure 6.2. BGA192 PCB Land Pattern Drawing

Table 7.1. BGA152 Package Dimensions

Dimension	Min	Typ	Max
A	0.78	0.84	0.90
A1	0.13	0.18	0.23
A3	0.16	0.20	0.24
A2	0.45 REF		
D	8.00 BSC		
e	0.50 BSC		
E	8.00 BSC		
D1	6.50 BSC		
E1	6.50 BSC		
b	0.20	0.25	0.30
aaa	0.10		
bbb	0.10		
ddd	0.08		
eee	0.15		
fff	0.05		

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.

8. BGA120 Package Specifications

8.1 BGA120 Package Dimensions

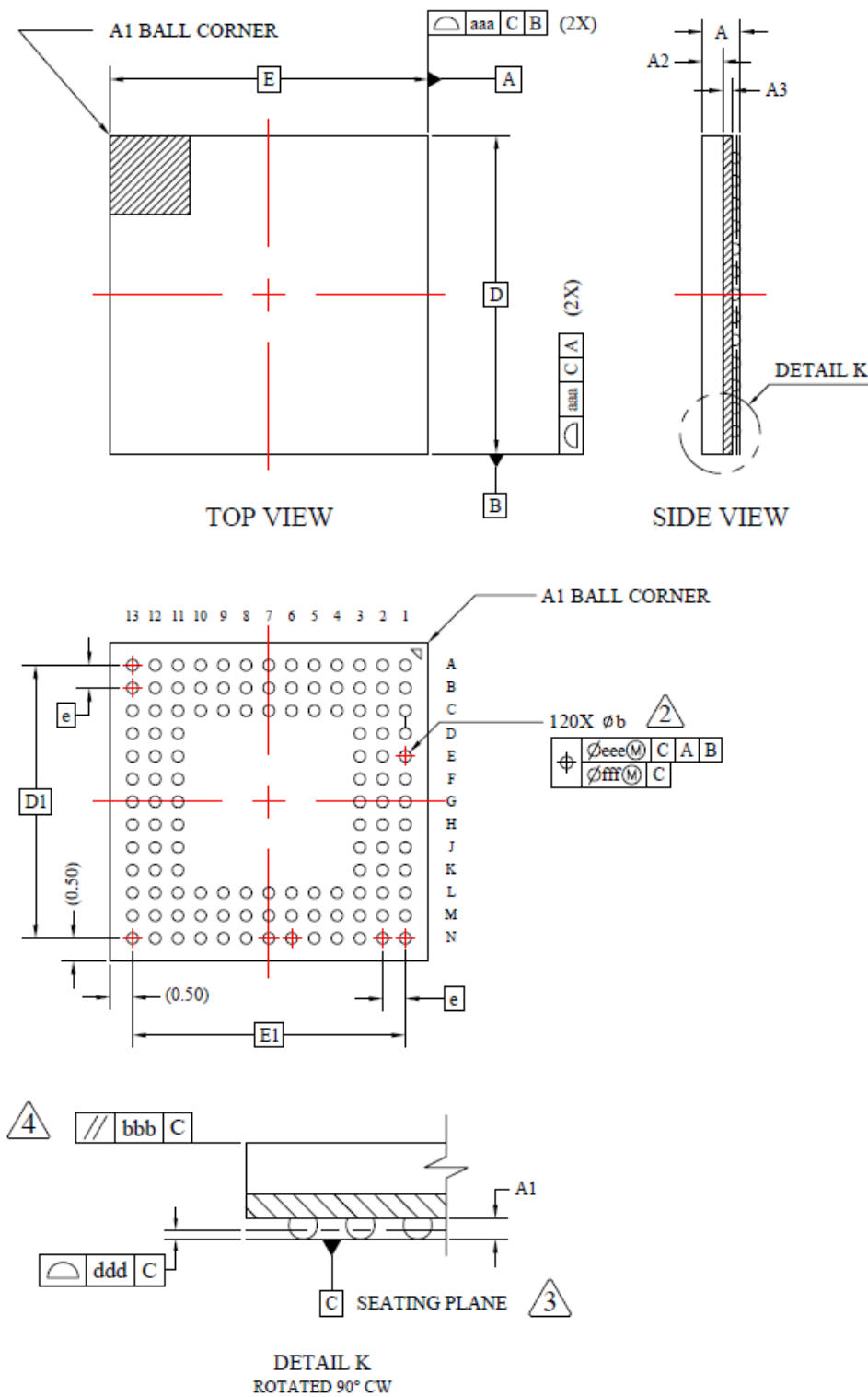


Figure 8.1. BGA120 Package Drawing

Table 8.2. BGA120 PCB Land Pattern Dimensions

Dimension	Min	Nom	Max
X		0.20	
C1		6.00	
C2		6.00	
E1		0.5	
E2		0.5	

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing is per the ANSI Y14.5M-1994 specification.
3. This Land Pattern Design is based on the IPC-7351 guidelines.
4. All metal pads are to be non-solder mask defined (NSMD). Clearance between the solder mask and the metal pad is to be 60 μ m minimum, all the way around the pad.
5. A stainless steel, laser-cut and electro-polished stencil with trapezoidal walls should be used to assure good solder paste release.
6. The stencil thickness should be 0.125 mm (5 mils).
7. The ratio of stencil aperture to land pad size should be 1:1.
8. A No-Clean, Type-3 solder paste is recommended.
9. The recommended card reflow profile is per the JEDEC/IPC J-STD-020C specification for Small Body Components.

9.3 BGA112 Package Marking



Figure 9.3. BGA112 Package Marking

The package marking consists of:

- P P P P P P P P P P – The part number designation.
- T T T T T T – A trace or manufacturing code. The first letter is the device revision.
- Y Y – The last 2 digits of the assembly year.
- W W – The 2-digit workweek when the device was assembled.

11. TQFP64 Package Specifications

11.1 TQFP64 Package Dimensions

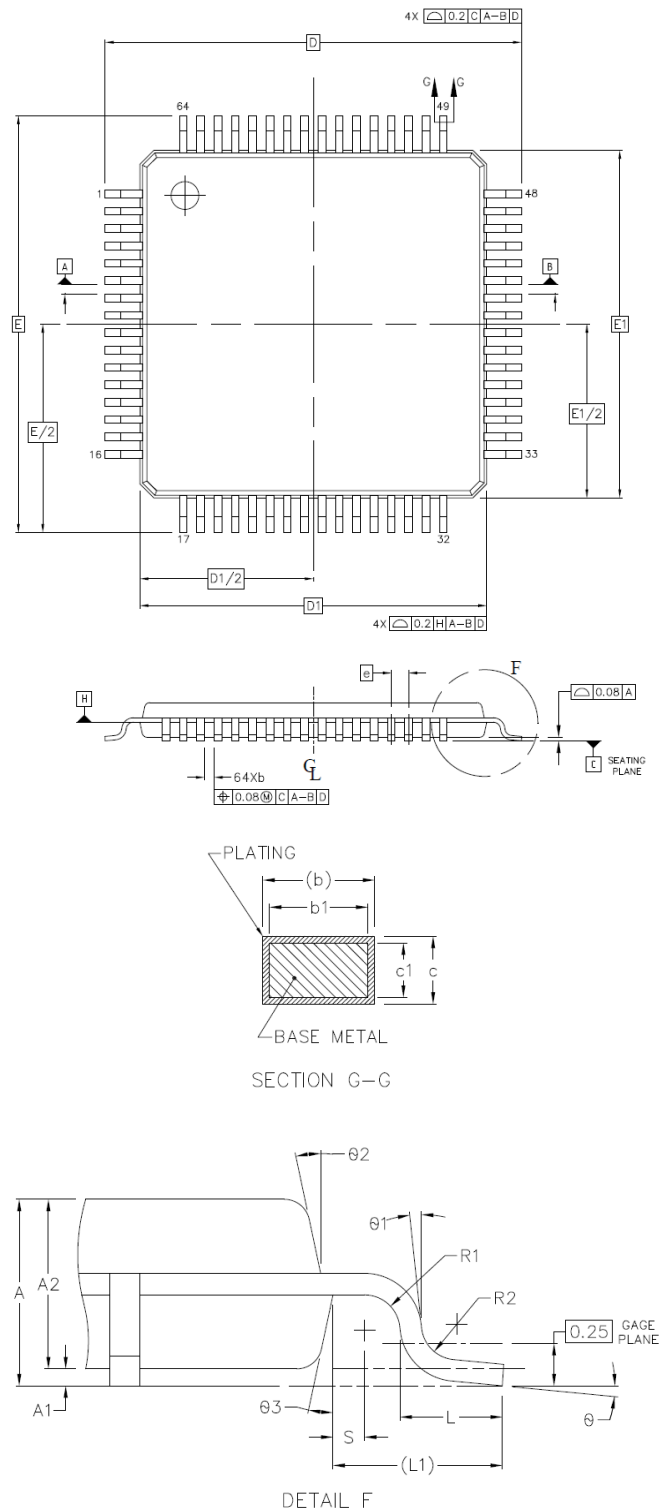


Figure 11.1. TQFP64 Package Drawing

11.2 TQFP64 PCB Land Pattern

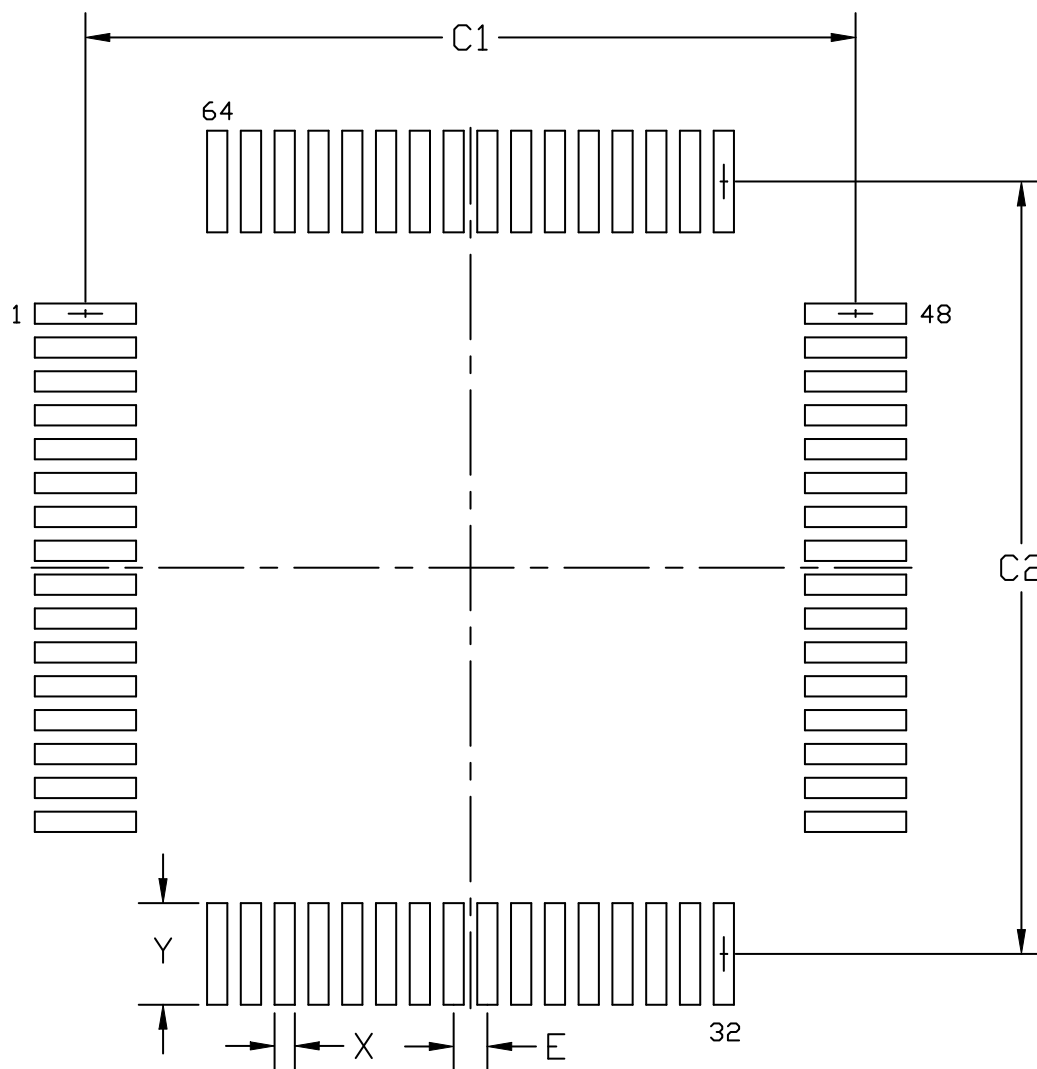


Figure 11.2. TQFP64 PCB Land Pattern Drawing